3.3V CMOS 18-BIT UNIVERSAL BUS TRANSCEIVER WITH 3-STATE OUTPUTS, 5 VOLT TOLERANT I/O, BUS-HOLD

IDT74LVCH16601A
OBSOLETE PART

FEATURES:

- Typical $t_{SK(o)}$ (Output Skew) < 250ps
- ESD > 2000V per MIL-STD-883, Method 3015; > 200V using machine model (C = 200pF, R = 0)
- V_{CC} = 3.3V ± 0.3V, Normal Range
- V_{CC} = 2.7V to 3.6V, Extended Range
- CMOS power levels (0.4µ W typ. static)
- All inputs, outputs, and I/O are 5V tolerant
- Supports hot insertion
- Available in SSOP package

DRIVE FEATURES:

- High Output Drivers: ±24mA
- Reduced system switching noise

APPLICATIONS:

- 5V and 3.3V mixed voltage systems
- Data communication and telecommunication systems

DESCRIPTION:

The LVCH16601A 18-bit universal bus transceiver is built using advanced dual metal CMOS technology. The LVCH16601A combines D-type latches and D-type flip-flops to allow data flow in transparent, latched and clocked modes.

Data flow in each direction is controlled by output-enable ($\overline{OEAB}$ and $\overline{OEBA}$), latched-enable (LEAB and LEBA), and clock (CLKAB and CLKBA) inputs. The clock can be controlled by the clock-enable ($\overline{CLKENAB}$ and $\overline{CLKENBA}$) inputs.

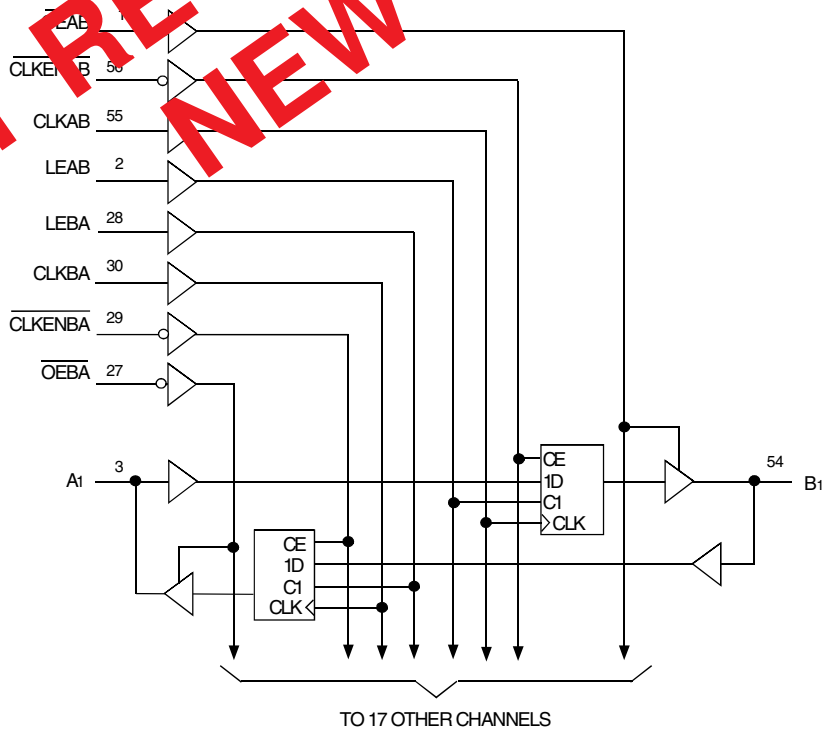
For A-to-B data flow, the device operates in the transparent mode when LEAB is high. When LEAB is low, the A data is latched if CLKAB is held at a high or low logic level. If LEAB is low, the A-bus data is stored in the latch/flip-flop on the low-to-high transition of CLKAB. Output enable $\overline{OEAB}$ is active low. When $\overline{OEAB}$ is low, the outputs are active. When $\overline{OEAB}$ is high, the outputs are in the high-impedance state. Data flow for B to A is similar to that of A to B but uses $\overline{OEBA}$, LEBA, CLKBA and $\overline{CLKENBA}$.

All pins can be driven from either 3.3V or 5V devices. This feature allows the use of this device as a translator in a mixed 3.3V/5V supply system.

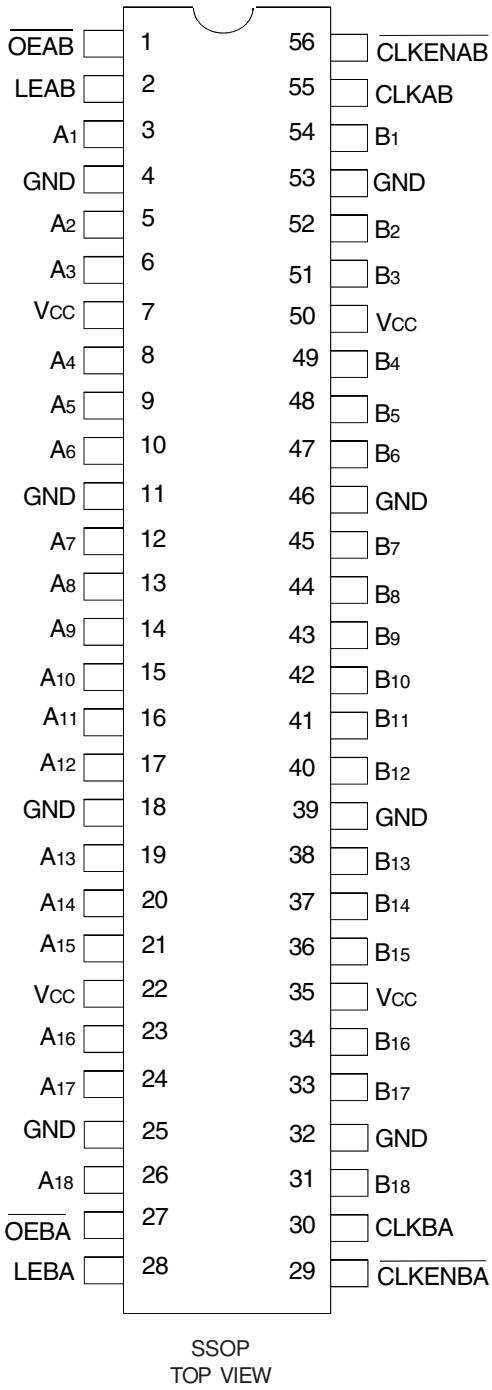
The LVCH16601A has been designed with a ±24mA output driver. This driver is capable of driving a moderate to heavy load while maintaining speed performance.

The LVCH16601A has "bus-hold" which retains the inputs' last state whenever the input goes to a high impedance. This prevents floating inputs and eliminates the need for pull-up/down resistors.

FUNCTIONAL BLOCK DIAGRAM



PIN CONFIGURATION



SSOP
TOP VIEW

ABSOLUTE MAXIMUM RATINGS(1)

Symbol	Description	Max	Unit
V_{TERM}	Terminal Voltage with Respect to GND	–0.5 to +6.5	V
T_{STG}	Storage Temperature	–65 to +150	°C
I_{OUT}	DC Output Current	–50 to +50	mA
I_{IK} I_{OK}	Continuous Clamp Current, $V_I < 0$ or $V_O < 0$	–50	mA
I_{CC} I_{SS}	Continuous Current through each V_{CC} or GND	±100	mA

NOTE:
1. Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

PIN DESCRIPTION

Pin Names	Description
$\overline{OEAB}$	A-to-B Output Enable Input (Active LOW)
$\overline{OEBA}$	B-to-A Output Enable Input (Active LOW)
LEAB	A-to-B Latch Enable Input
LEBA	B-to-A Latch Enable Input
CLKAB	A-to-B Clock Input
CLKBA	B-to-A Clock Input
Ax	A-to-B Data Inputs or B-to-A 3-State Outputs(1)
Bx	B-to-A Data Inputs or A-to-B 3-State Outputs(1)
$\overline{CLKENAB}$	A-to-B Clock Enable Input (Active LOW)
$\overline{CLKENBA}$	B-to-A Clock Enable Input (Active LOW)

NOTE:
1. These pins have "Bus-Hold". All other pins are standard inputs, outputs, or I/Os.

FUNCTION TABLE(1,2)

Inputs					Outputs
$\overline{CLKENAB}$	$\overline{OEAB}$	LEAB	CLKAB	Ax	Bx
X	H	X	X	X	Z
X	L	H	X	L	L
X	L	H	X	H	H
H	L	L	X	X	B(3)
L	L	L	↑	L	L
L	L	L	↑	H	H
L	L	L	L	X	B(3)
L	L	L	H	X	B(4)

NOTES:
1. H = HIGH Voltage Level
   X = Don't Care
   L = LOW Voltage Level
   Z = High-Impedance
   ↑ = LOW-to-HIGH transition
2. A-to-B data flow is shown. B-to-A data flow is similar but uses $\overline{OEBA}$, LEBA, CLKBA, and $\overline{CLKENBA}$.
3. Output level before the indicated steady-state input conditions were established.
4. Output level before the indicated steady-state input conditions were established, provided that CLKAB was HIGH before LEAB went LOW.

CAPACITANCE (T_A = +25°C, F = 1.0MHz)

Symbol	Parameter(1)	Conditions	Typ.	Max.	Unit
C_{IN}	Input Capacitance	V_{IN} = 0V	4.5	6	pF
C_{OUT}	Output Capacitance	V_{OUT} = 0V	6.5	8	pF
$C_{I/O}$	I/O Port Capacitance	V_{IN} = 0V	6.5	8	pF

NOTE:
1. As applicable to the device type.

DC ELECTRICAL CHARACTERISTICS OVER OPERATING RANGE

Following Conditions Apply Unless Otherwise Specified:
Operating Condition: $T_A = -40°C$ to $+85°C$

Symbol	Parameter	Test Conditions		Min.	Typ.(1)	Max.	Unit
V_{IH}	Input HIGH Voltage Level	V_{CC} = 2.3V to 2.7V		1.7	—	—	V
		V_{CC} = 2.7V to 3.6V		2	—	—	
V_{IL}	Input LOW Voltage Level	V_{CC} = 2.3V to 2.7V		—	—	0.7	V
		V_{CC} = 2.7V to 3.6V		—	—	0.8	
I_{IH} I_{IL}	Input Leakage Current	V_{CC} = 3.6V	V_I = 0 to 5.5V	—	—	±5	µA
I_{OZH} I_{OZL}	High Impedance Output Current (3-State Output pins)	V_{CC} = 3.6V	V_O = 0 to 5.5V	—	—	±10	µA
I_{OFF}	Input/Output Power Off Leakage	V_{CC} = 0V, V_{IN} or $V_O \leq$ 5.5V		—	—	±50	µA
V_{IK}	Clamp Diode Voltage	V_{CC} = 2.3V, I_{IN} = –18mA		—	–0.7	–1.2	V
V_H	Input Hysteresis	V_{CC} = 3.3V		—	100	—	mV
I_{CCL} I_{CCH}	Quiescent Power Supply Current	V_{CC} = 3.6V	V_{IN} = GND or V_{CC}	—	—	10	µA
I_{CCZ}			3.6 ≤ V_{IN} ≤ 5.5V(2)	—	—	10	
ΔI_{CC}	Quiescent Power Supply Current Variation	One input at V_{CC} - 0.6V, other inputs at V_{CC} or GND		—	—	500	µA

NOTES:
1. Typical values are at V_{CC} = 3.3V, +25°C ambient.
2. This applies in the disabled state only.

BUS-HOLD CHARACTERISTICS

Symbol	Parameter(1)	Test Conditions		Min.	Typ.(2)	Max.	Unit
I_{BHH}	Bus-Hold Input Sustain Current	V_{CC} = 3V	V_I = 2V	–75	—	—	µA
I_{BHL}			V_I = 0.8V	75	—	—	
I_{BHH}	Bus-Hold Input Sustain Current	V_{CC} = 2.3V	V_I = 1.7V	—	—	—	µA
I_{BHL}			V_I = 0.7V	—	—	—	
I_{BHHO}	Bus-Hold Input Overdrive Current	V_{CC} = 3.6V	V_I = 0 to 3.6V	—	—	±500	µA
I_{BHLO}							

NOTES:
1. Pins with Bus-Hold are identified in the pin description.
2. Typical values are at V_{CC} = 3.3V, +25°C ambient.

OUTPUT DRIVE CHARACTERISTICS

Symbol	Parameter	Test Conditions[1]		Min.	Max.	Unit
V_{OH}	Output HIGH Voltage	V_{CC} = 2.3V to 3.6V	I_{OH} = – 0.1mA	V_{CC} – 0.2	—	V
		V_{CC} = 2.3V	I_{OH} = – 6mA	2	—	
		V_{CC} = 2.3V	I_{OH} = – 12mA	1.7	—	
		V_{CC} = 2.7V		2.2	—	
		V_{CC} = 3V		2.4	—	
		V_{CC} = 3V	I_{OH} = – 24mA	2	—	
V_{OL}	Output LOW Voltage	V_{CC} = 2.3V to 3.6V	I_{OL} = 0.1mA	—	0.2	V
		V_{CC} = 2.3V	I_{OL} = 6mA	—	0.4	
			I_{OL} = 12mA	—	0.7	
		V_{CC} = 2.7V	I_{OL} = 12mA	—	0.4	
		V_{CC} = 3V	I_{OL} = 24mA	—	0.55	

NOTE:
1. V_{IH} and V_{IL} must be within the min. or max. range shown in the DC ELECTRICAL CHARACTERISTICS OVER OPERATING RANGE table for the appropriate V_{CC} range. T_A = – 40°C to + 85°C.

OPERATING CHARACTERISTICS, V_{CC} = 3.3V ± 0.3V, T_A = 25°C

Symbol	Parameter	Test Conditions	Typical	Unit
C_{PD}	Power Dissipation Capacitance per Transceiver Outputs enabled	C_L = 0pF, f = 10Mhz		pF
C_{PD}	Power Dissipation Capacitance per Transceiver Outputs disabled			

SWITCHING CHARACTERISTICS(1)

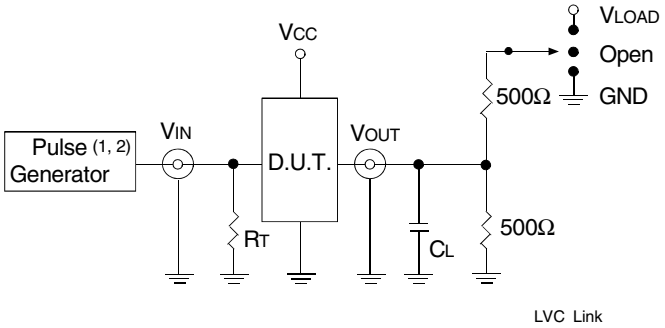
Symbol	Parameter		V_{CC} = 2.7V		V_{CC} = 3.3V ± 0.3V		Unit
			Min.	Max.	Min.	Max.	
t_{PLH} t_{PHL}	Propagation Delay Ax to Bx or Bx to Ax		—	5.4	—	4.6	ns
t_{PLH} t_{PHL}	Propagation Delay LEBA to Ax, LEAB to Bx		—	6.2	—	5.2	ns
t_{PLH} t_{PHL}	Propagation Delay CLKBA to Ax, CLKAB to Bx		—	6.3	—	5.3	ns
t_{PZH} t_{PZL}	Output Enable Time $\overline{OEBA}$ to Ax, $\overline{OEAB}$ to Bx		—	6.8	—	5.6	ns
t_{PHZ} t_{PLZ}	Output Disable Time $\overline{OEBA}$ to Ax, $\overline{OEAB}$ to Bx		—	6	—	5.2	ns
t_{SU}	Set-up Time HIGH or LOW Ax to CLKAB, Bx to CLKBA		1.5	—	1.5	—	ns
t_H	Hold Time HIGH or LOW Ax to CLKAB, Bx to CLKBA		0.8	—	0.8	—	ns
t_{SU}	Set-up Time HIGH or LOW Ax to LEAB, Bx to LEBA	Clock LOW Clock HIGH	1 1	— —	1 1	— —	ns
t_{SU}	Set-up Time, $\overline{CLKENAB}$ to CLKAB		2.1	—	2.1	—	ns
t_{SU}	Set-up Time, $\overline{CLKENBA}$ to CLKBA		2.1	—	2.1	—	ns
t_H	Hold Time HIGH or LOW Ax after LEAB, Bx after LEBA		1.8	—	1.8	—	ns
t_H	Hold Time, $\overline{CLKENAB}$ after CLKAB		0.5	—	0.5	—	ns
t_H	Hold Time, $\overline{CLKENBA}$ after CLKBA		0.5	—	0.5	—	ns
t_W	LEAB or LEBA Pulse Width HIGH		3	—	3	—	ns
t_W	CLKAB or CLKBA Pulse Width HIGH or LOW		3	—	3	—	ns
$t_{SK(o)}$	Output Skew(2)		—	—	—	500	ps

NOTES:
1. See TEST CIRCUITS AND WAVEFORMS. T_A = – 40°C to + 85°C.
2. Skew between any two outputs of the same package and switching in the same direction.

TEST CIRCUITS AND WAVEFORMS

TEST CONDITIONS

Symbol	$V_{CC}^{(1)}$=3.3V±0.3V	$V_{CC}^{(1)}$=2.7V	$V_{CC}^{(2)}$=2.5V±0.2V	Unit
V_{LOAD}	6	6	2 x Vcc	V
V_{IH}	2.7	2.7	Vcc	V
V_T	1.5	1.5	Vcc / 2	V
V_{LZ}	300	300	150	mV
V_{HZ}	300	300	150	mV
C_L	50	50	30	pF



Test Circuit for All Outputs

DEFINITIONS:

C_L = Load capacitance: includes jig and probe capacitance.

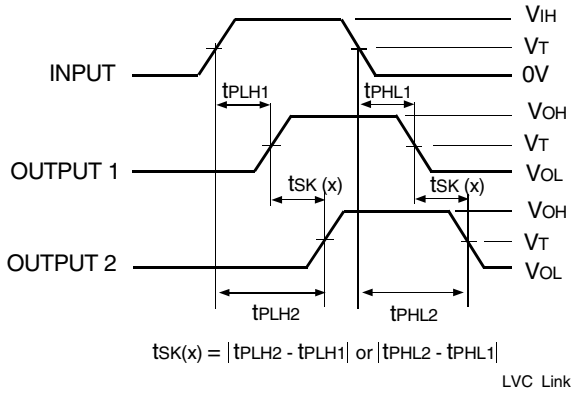
R_T = Termination resistance: should be equal to Z_{OUT} of the Pulse Generator.

NOTES:

1. Pulse Generator for All Pulses: Rate ≤ 10MHz; t_F ≤ 2.5ns; t_R ≤ 2.5ns.
2. Pulse Generator for All Pulses: Rate ≤ 10MHz; t_F ≤ 2ns; t_R ≤ 2ns.

SWITCH POSITION

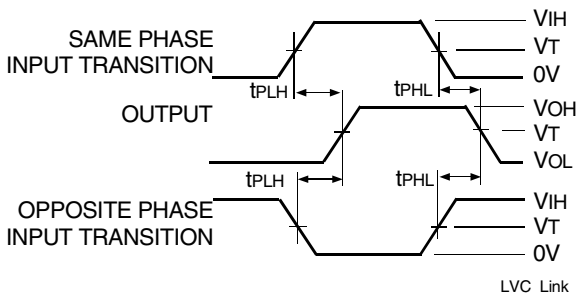
Test	Switch
Open Drain Disable Low Enable Low	V_{LOAD}
Disable High Enable High	GND
All Other Tests	Open



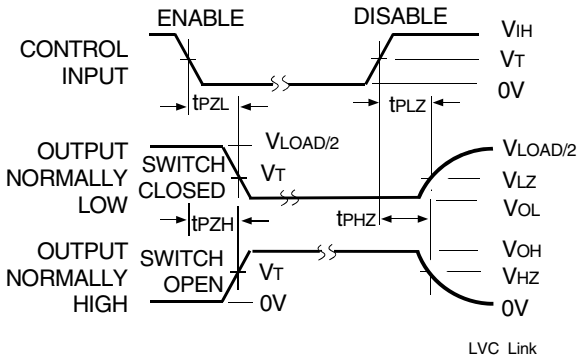
Output Skew - $t_{SK}(x)$

NOTES:

1. For t_{SK}(o) OUTPUT1 and OUTPUT2 are any two outputs.
2. For t_{SK}(b) OUTPUT1 and OUTPUT2 are in the same bank.



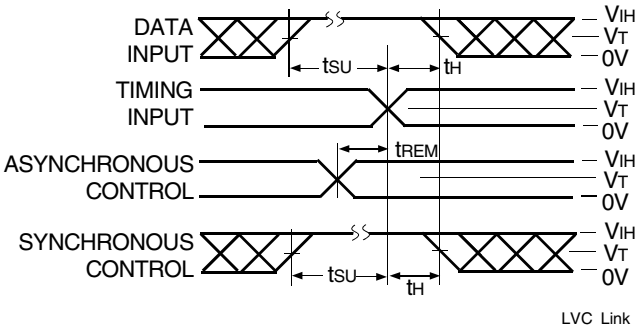
Propagation Delay



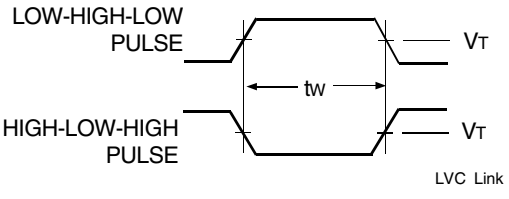
Enable and Disable Times

NOTE:

1. Diagram shown for input Control Enable-LOW and input Control Disable-HIGH.

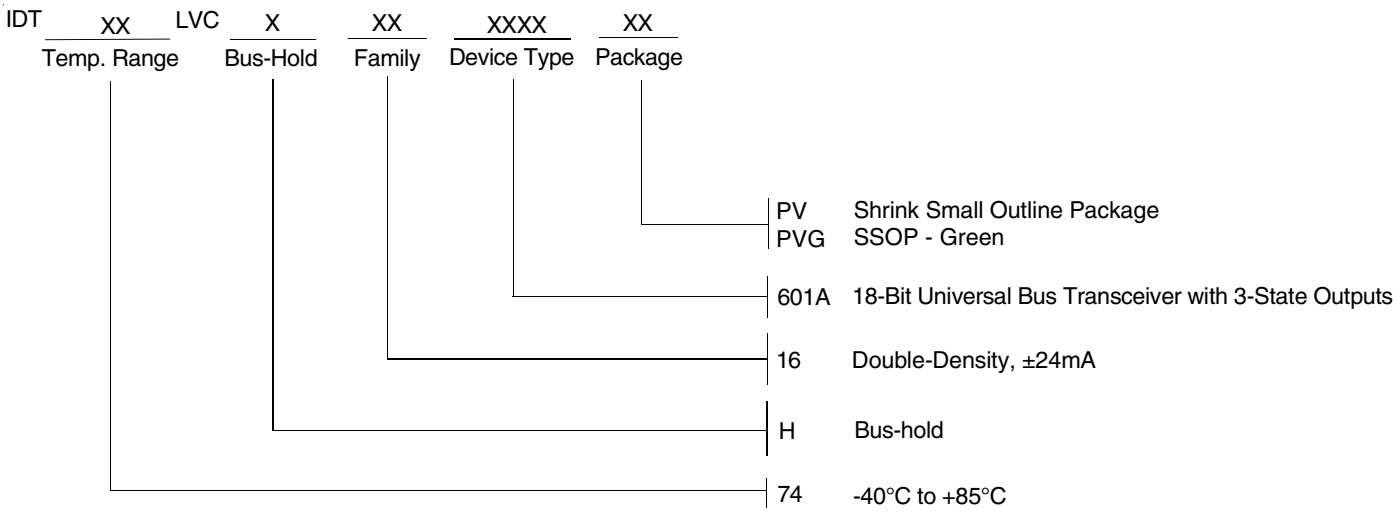


Set-up, Hold, and Release Times



Pulse Width

ORDERING INFORMATION



DATASHEET DOCUMENT HISTORY

10/28/2013	PDN# CQ-13-03 issued. See IDT.com for PDN specifics.
09/06/2019	Datasheet changed to Obsolete Status.

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